

REMARKS

The last Office Action has been carefully amended.

Claim 1 has been amended herein to substantially incorporate the original claims 1 and 2. Claim2 has been canceled herein without prejudice or disclaimer to subject matter recited therein.

FIG.1 of the drawings has been amended and a red-marked correction sheet of FIG.1 is enclosed herewith. It is respectfully requested that this drawing objection be withdrawn.

The specification has been amended on page 2, lines 6-12. It is respectfully requested that the objection to the specification be withdrawn.

Claims 6-10 have been amended to fully comply with 35 U.S.C. 112, second paragraph. It is respectfully requested that this objection be withdrawn.

Claims 1-3 and 10 stand rejected under 35 U.S.C. 102 (e) as being anticipated by Marshall et al. (US 6,515,285). Claim 4 stand rejected under 35 U.S.C. 103 (a) over Marshall et al in view of Shih et al. (US 6,297,671). Claim 6 stands rejected under 35 U.S.C. 103 (a) over Marshall et al, Shih et al and Nagumo (US 6,028,472). Claims 7-9 stand rejected under 35 U.S.C. 103 (a) over Marshall et al, in view of Gordon (US 6,515,285).

Applicant respectfully traverses these rejections for the following reasons.

Amended claim 1 of the present application now recites a radiation sensor (10) of an integrated type which is provided with at least one light-sensitive and/or X-ray-sensitive sensor element (11) having an output signal that indicates the amount of radiation absorbed by the sensor element, and with at least one temperature sensor (12, 12a, 12b) having an output signal that indicates the temperature prevailing at the temperature sensor and also with at least one further sensor element (12) sensitive to a

physical quantity other than that which the light-sensitive and/or X-ray-sensitive sensor element (11) is sensitive, all sensor elements (11, 12) delivering similar output signals and being connectable to an evaluation unit (13) as similar components wherein said temperature sensor is integrated on said chip of said radiation sensor , said chip having a substantially uniform temperature distribution so that temperature sensed by said temperature sensor corresponds to the temperature of the entire radiation sensor chip enabling direct and accurate determination of the temperature at the radiation sensor (emphasis added). Support for this feature can be found on page 2, lines 16-24 of the present specification.

The patent to Marshall et al. relates compensating a radiation sensor for ambient temperature variations. This patent is concerned with ambient temperature variations and compensating a radiation sensor these variations. Marshall does not disclose or suggest a radiation sensor in which the chip having a substantially uniform temperature distribution so that temperature sensed by said temperature sensor corresponds to the temperature of the entire radiation sensor chip enabling direct and accurate determination of the temperature at the radiation sensor. Accordingly , it is respectfully submitted that amended claim1 is not taught or suggested by the patent to Marshall et al , either alone or in combination with the cited references of Shih et al, Nagumo or Gordon.

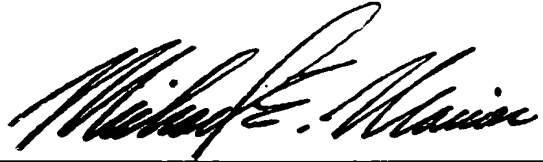
The rest of the claims 2-13 depend on claim 1, directly or indirectly, and are therefore believed to be allowable for the aforementioned reasons.

New dependent claims 11,212 and 13 are supported by the specification. Notably page 3, lines 23-30 support claims 11 and 12 and page 5, lines 13-24 support claim 13. These features recite subject are not disclosed or suggested by Marshall et al., Shih, et al, Nagumo or Gordon, alone or in combination.

Accordingly, it is respectfully submitted that none of the references in the last office action, alone or in combination, teach or suggest the claims remaining in the present application.

Allowance of the claims remaining in the present application is earnestly solicited.

Respectfully submitted,



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CERTIFICATE OF MAILING

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IN THE DRAWINGS

Please replace FIG.1 with the red-marked corrected drawing of FIG.1 enclosed herein.